

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Chen-Hua Yu</td><td>06/22/2011</td></tr><tr><td>Jing-Cheng Lin</td><td>06/22/2011</td></tr><tr><td>Nai-Wei Liu</td><td>06/22/2011</td></tr><tr><td>Jui-Pin Hung</td><td>06/22/2011</td></tr><tr><td>Shin-Puu Jeng</td><td>06/23/2011</td></tr></tbody></table>		Name	Execution Date	Chen-Hua Yu	06/22/2011	Jing-Cheng Lin	06/22/2011	Nai-Wei Liu	06/22/2011	Jui-Pin Hung	06/22/2011	Shin-Puu Jeng	06/23/2011
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<table border="1"><tr><td>Name:</td><td>Taiwan Semiconductor Manufacturing Company, Ltd.</td></tr><tr><td>Street Address:</td><td>No. 8, Li-Hsin Rd. 6</td></tr><tr><td>Internal Address:</td><td>Science-Based Industrial Park</td></tr><tr><td>City:</td><td>Hsin-Chu</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr><tr><td>Postal Code:</td><td>300-77 R.O.C.</td></tr></table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77 R.O.C.
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number: (972)732-9218 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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Email: edwards@slater-matsil.com													
Correspondent Name: Slater & Matsil, L.L.P.													
Address Line 1: 17950 Preston Road													
Address Line 2: Suite 1000													
Address Line 4: Dallas, TEXAS 75252													
ATTORNEY DOCKET NUMBER:	TSM11-0150												

501605476

PATENT
REEL: 026644 FRAME: 0607

CH \$40.00 13170973

NAME OF SUBMITTER:

Kasey Edwards

Total Attachments: 2

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ATTORNEY DOCKET NO.
TSM11-0150

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

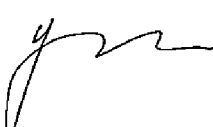

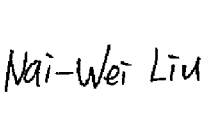
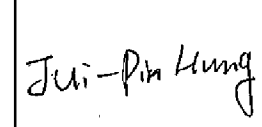
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Interconnect Structure for Wafer Level Package</i>			
SIGNATURE OF INVENTOR AND NAME	 Chen-HuaYu	 Jing-ChengLin	 Nai-Wei Liu	 Jui-Pin Hung
DATE	6/22/11	2011/06/22	2011/06/22	2011/06/22
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan	Fengshan City, Taiwan	Hsin-Chu, Taiwan

ATTORNEY DOCKET NO.
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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and


WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Interconnect Structure for Wafer Level Package</i>			
SIGNATURE OF INVENTOR AND NAME	 Shin-PuuJeng			
DATE	2011/6/23			
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